



## 2° MEETING IU.NET

Udine, 10-11 Febbraio 2011

# Le Attività di IU.NET nel Progetto PULLNANO

[www.pullnano.eu](http://www.pullnano.eu)

Luca Selmi

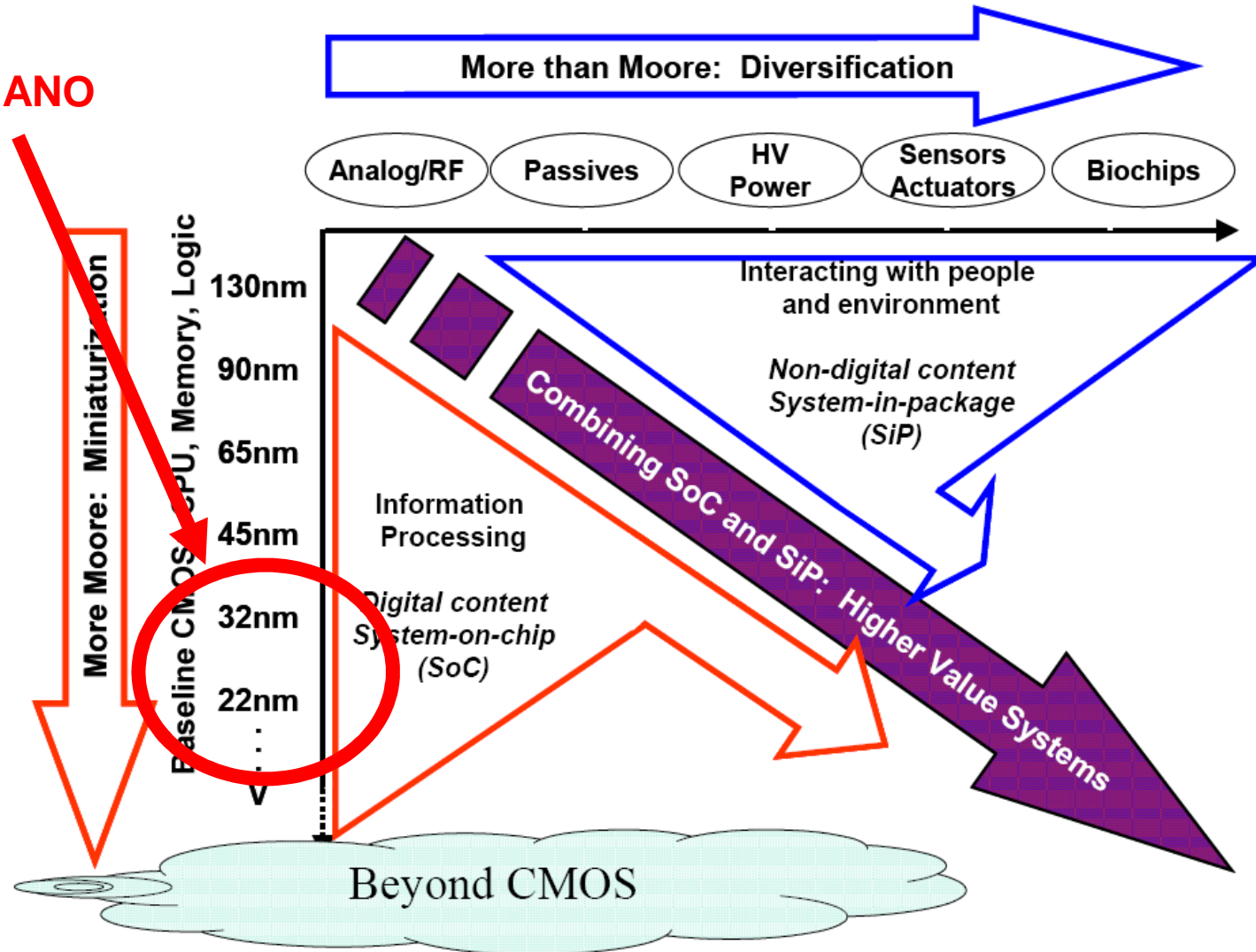
IU.NET- DIEGM - Università di Udine



SAPIENZA  
UNIVERSITÀ DI ROMA

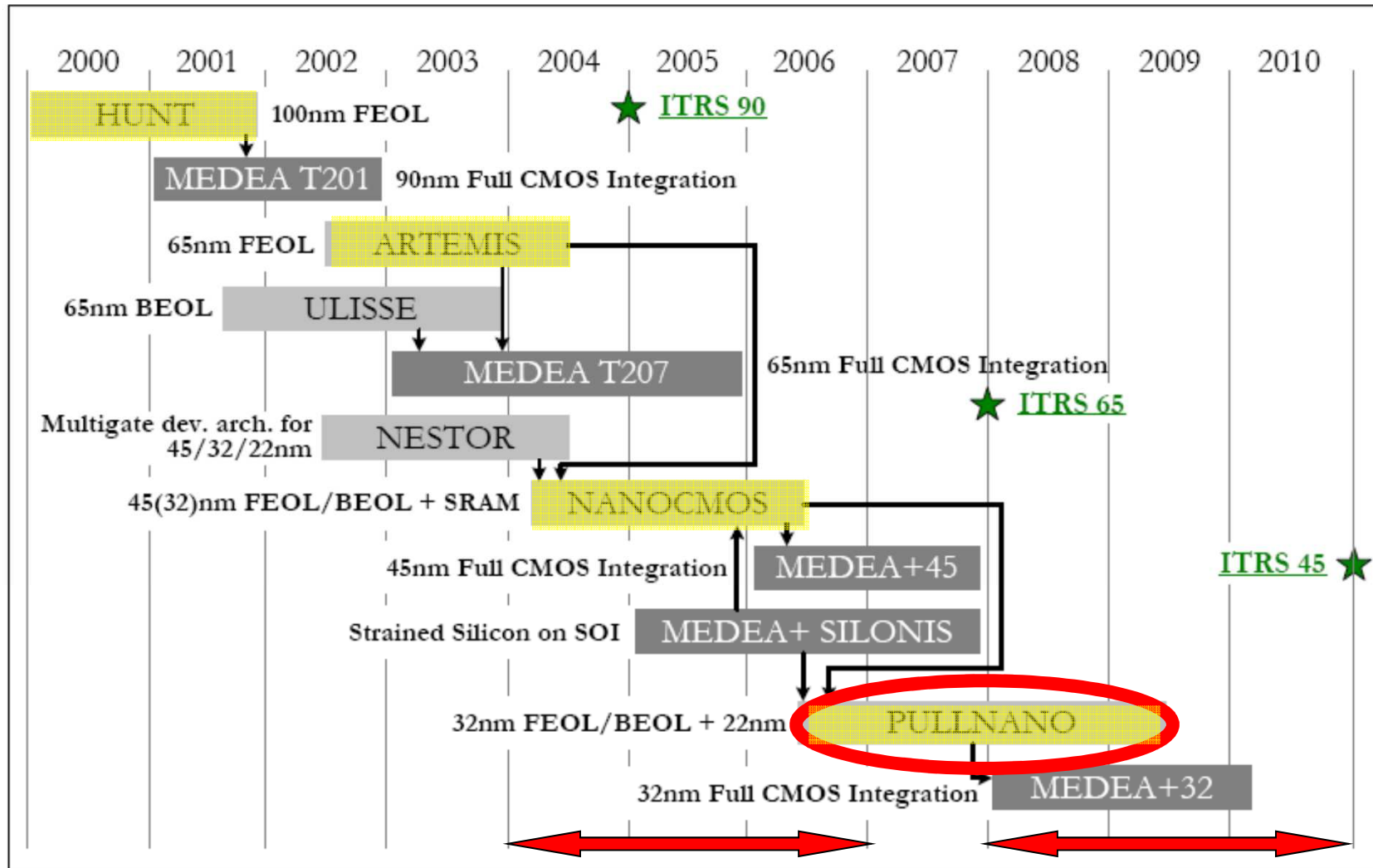


**PULLNANO**

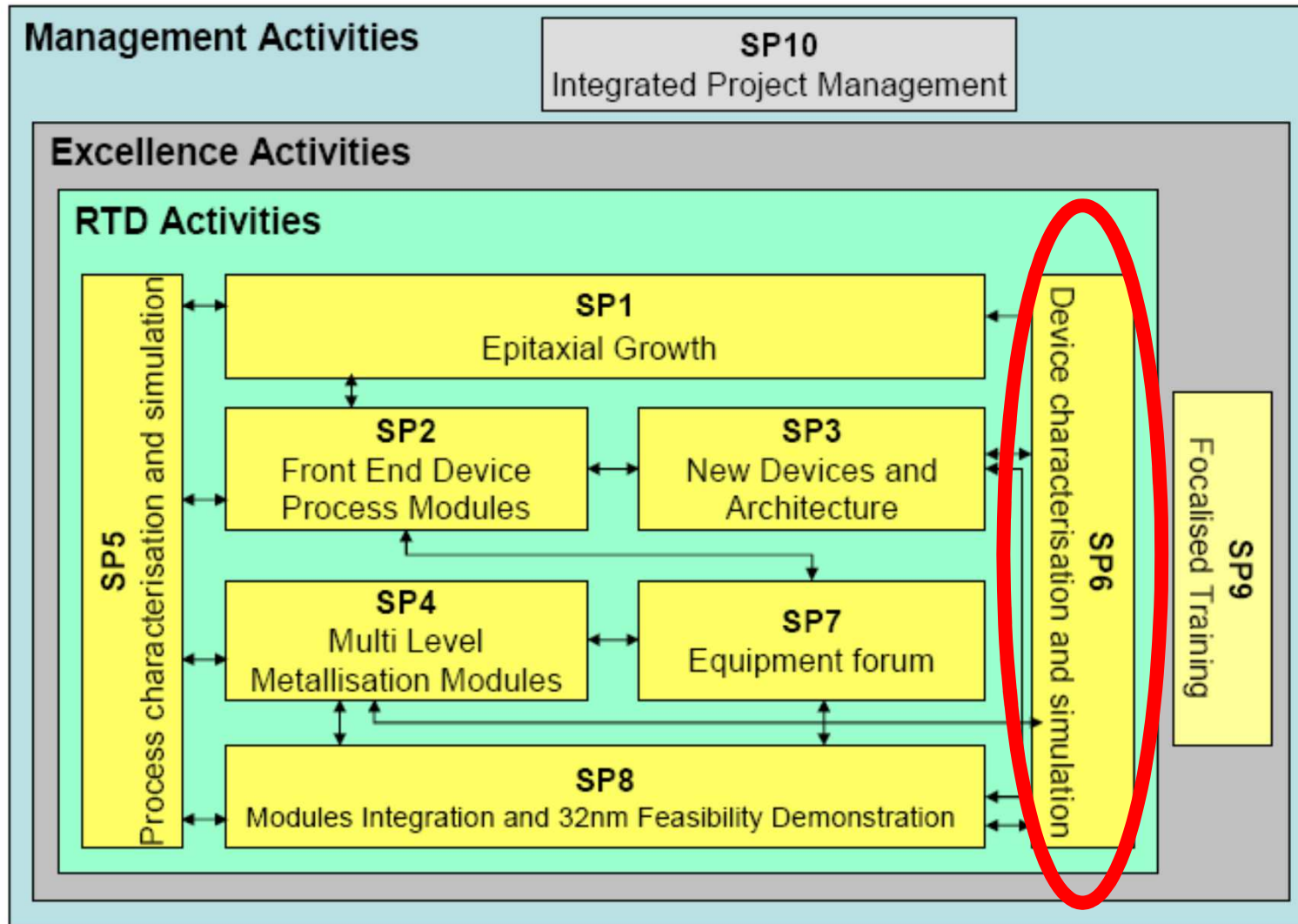


[ITRS, 2005]

1. Demonstrate feasibility of 32nm CMOS technology through an SRAM test vehicle (bulk, SOI, FinFET).
2. Prepare the 22nm node in terms of modeling, materials, devices, interconnect scheme, characterization.
3. Boost synergy Technology/Design to cope with power and interconnect delay limitations.
4. To be a forum of European equipment suppliers for the establishment of future tool specifications.



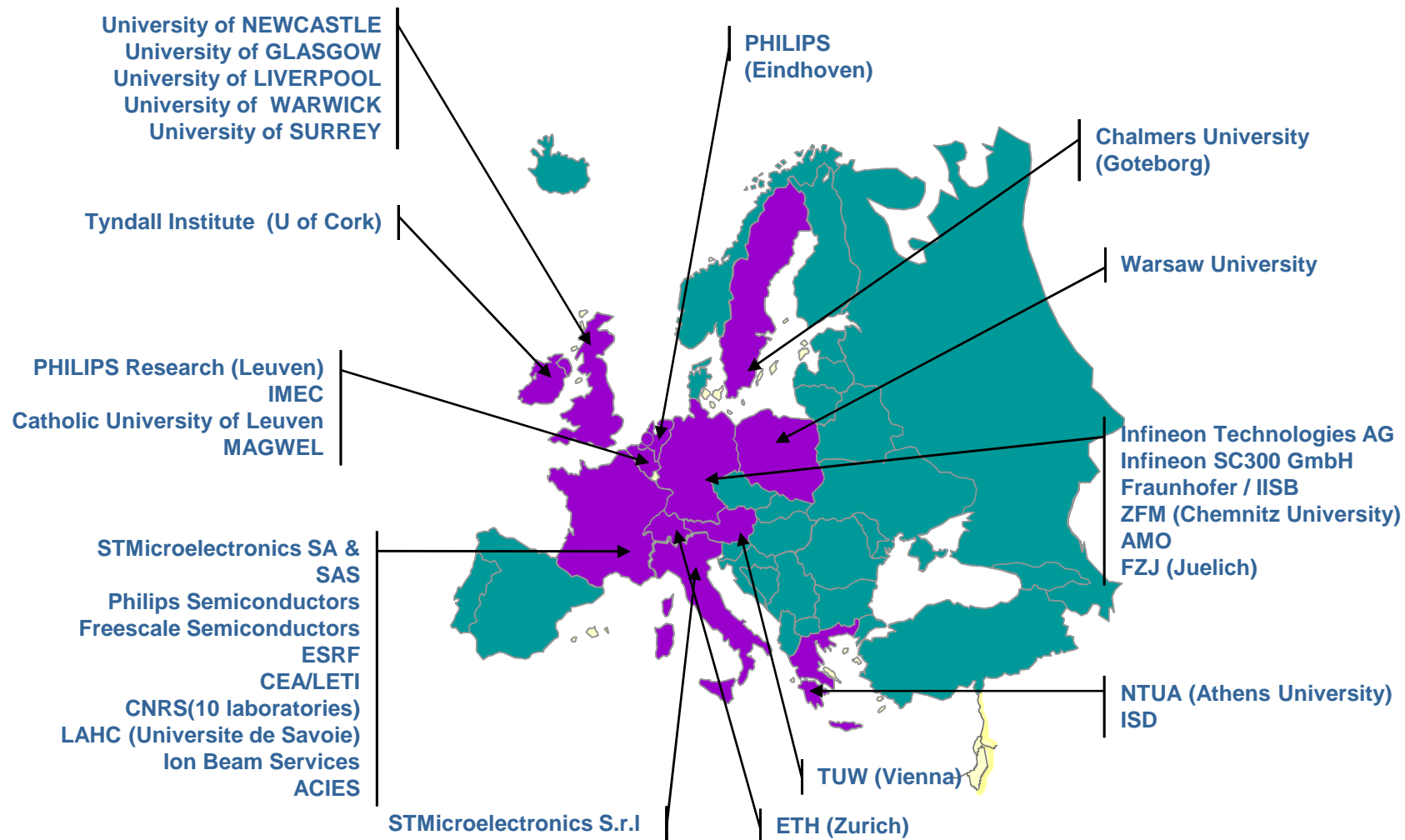
- 2001: tentativo di aggregare i partner accademici europei per competere sugli ultimi 20Meuro di FP5.
- Enorme scetticismo verso accademia
- Player industriali rispondono con il progetto NESTOR
- Quale ruolo per i partner accademici ? Quale modello per le relazioni Industria-Accademia nel settore semiconduttori ?
- SINANO e NANOCMOS
  
- Necessità di superare la frammentazione
- Necessità di superare il dualismo Industria-Accademia
- Cluster accademico «immerso» nel progetto





# The PULLNANO Consortium

35 PARTERS in 12 EUROPEAN Countries



**IU.NET (cluster of 8 universities)**



# SP6 expected breakthroughs

- Advanced modeling and simulations
  - new physical models for transport and fluctuations
- TCAD simulation:
  - device design and specification, strain, benchmarking
- Compact modeling:
  - new compact models, transfer to MASTAR
- Electrical characterization:
  - mobility in short devices, high-k dielectric quality assessment



- Develop advanced physical models addressing the needs foreseen for the 32 nm and 22nm TN:
  - strained silicon / thin semiconductor films
  - adoption of different crystal orientations for the channel
  - high-k gate dielectrics
  - Sources of fluctuations (dopants, traps, dielectric and silicon layer thickness, line-edge roughness, ...)
- Implement the models in device simulators
- Compare different device architectures and technological options
- Compare the simulation tools

**Total funding by EC: 25 M€ for 30 months**

**Cluster 6.4 (first 18 months):**

– IU.NET	0.55
– ETH	0.16
– UGLA	0.15
– WUT	0.07
– CNRS	0.07

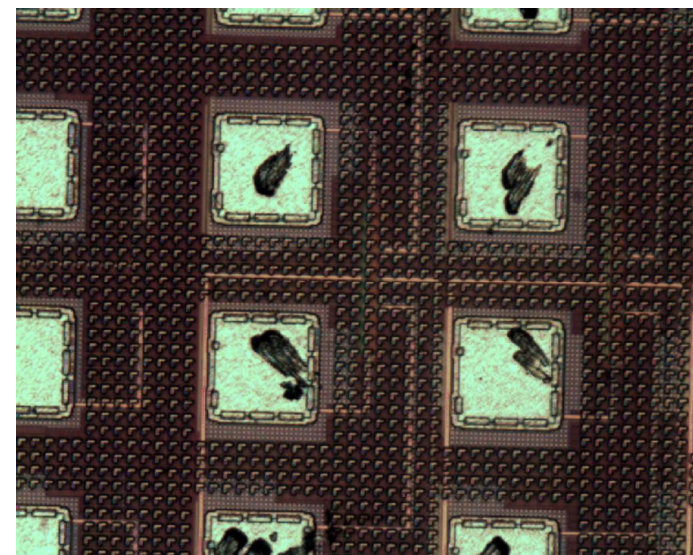
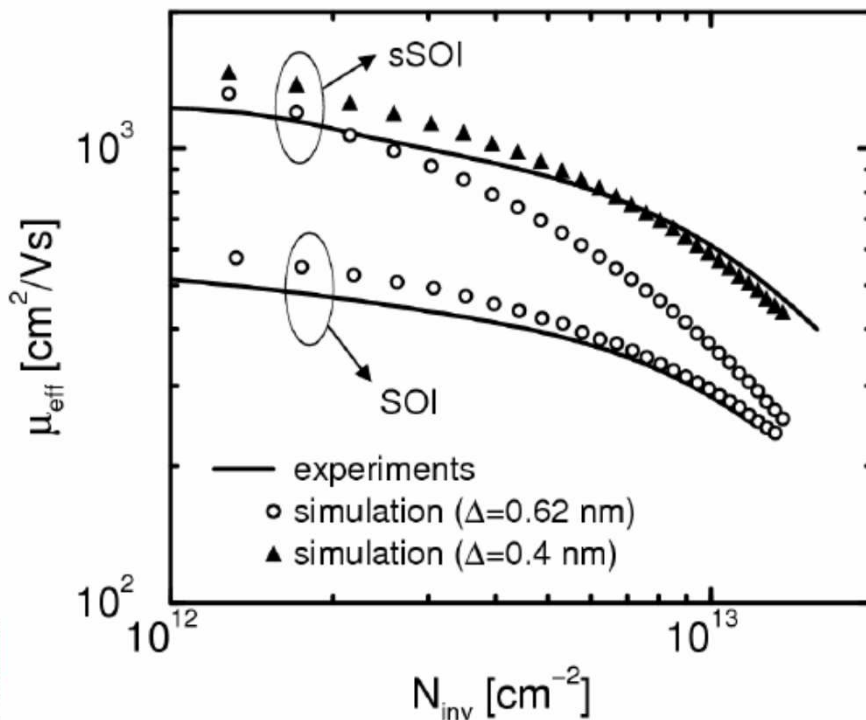
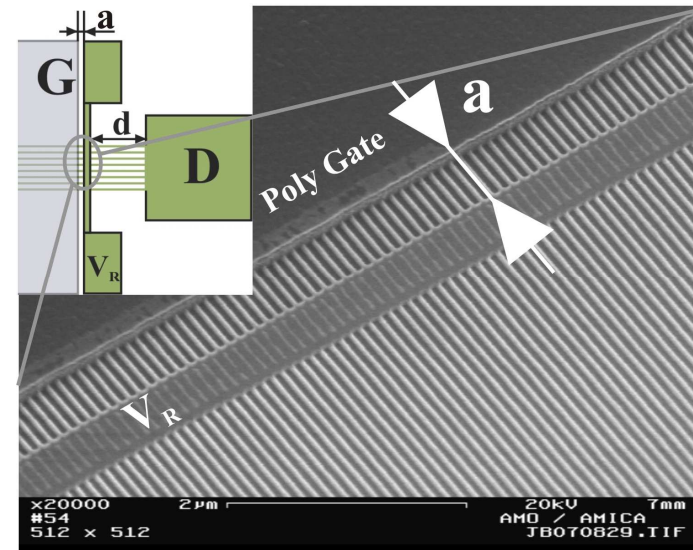
**IU.NET (first 18 months) : 120 p.months**

**IU.NET internal breakdown**

– University of Bologna	≈ 0.32
– University of Udine	≈ 0.32
– Politecnico of Milan	≈ 0.16
– University of Pisa	≈ 0.16
– IU.NET	≈ 0.04

Mobility test structures in planar and FinFET technology (different substrates, strain levels, crystal orientation, etc...)

Porting of the test structures into STM, LETI and IMEC mask sets



# MSMC: development and applications (UD)

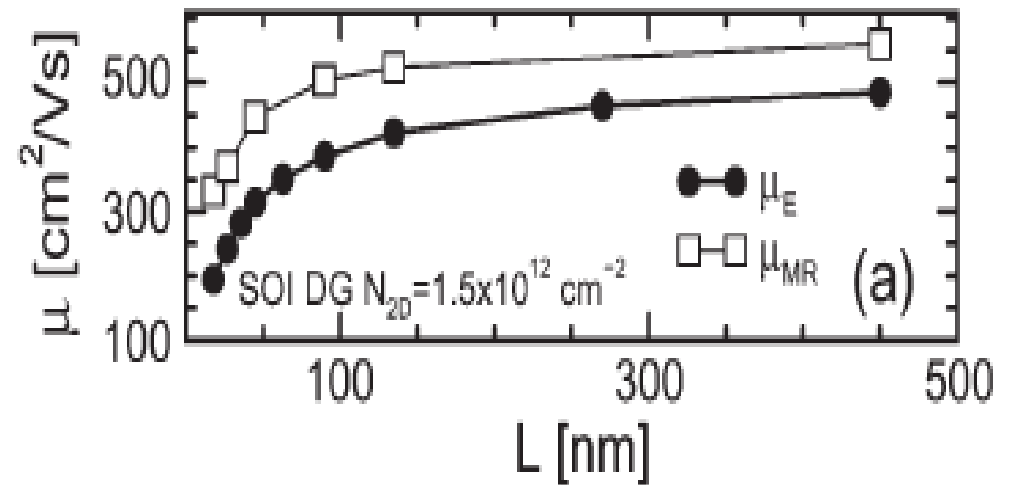
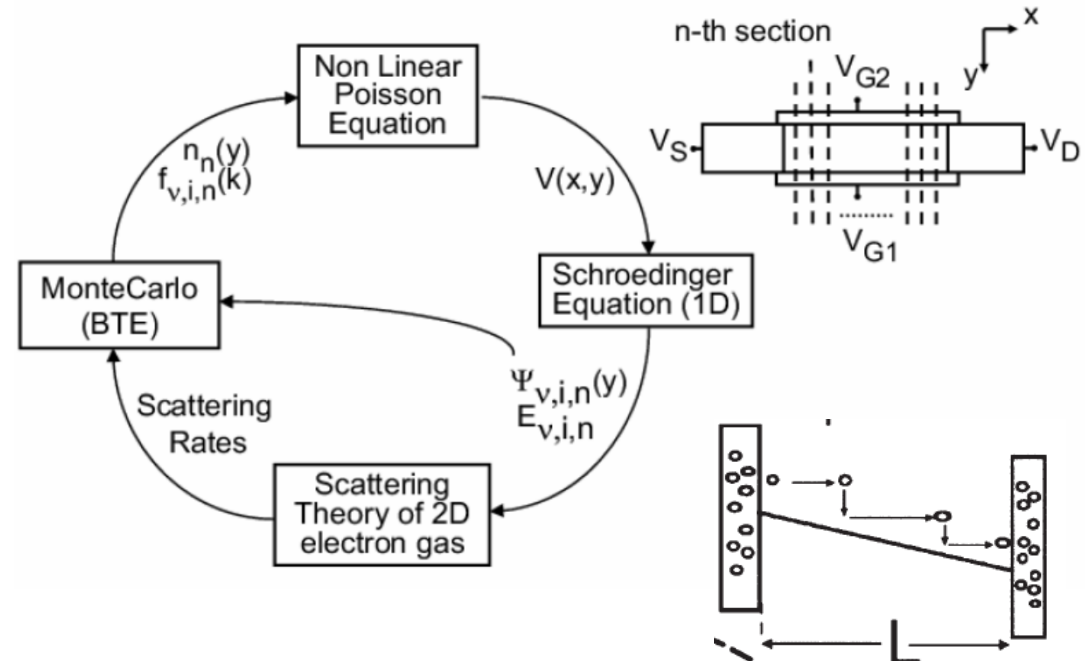
Develop transport models to predict the  $I_{ON}$  of nanoscale devices

- ballistic mobility
- high-k dielectrics
- strain engineering

Understand the effectiveness of the technology boosters and the distance from the theoretical limits

Benchmarking characterization techniques

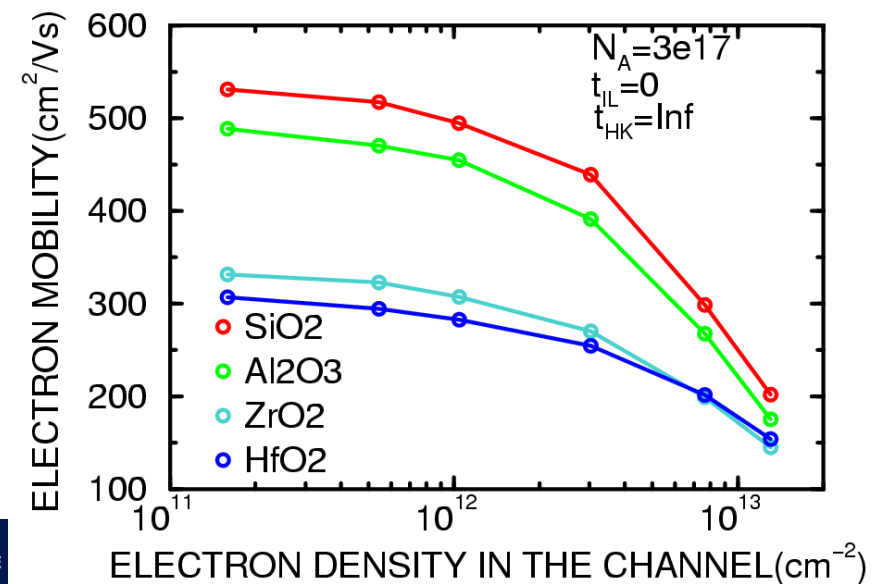
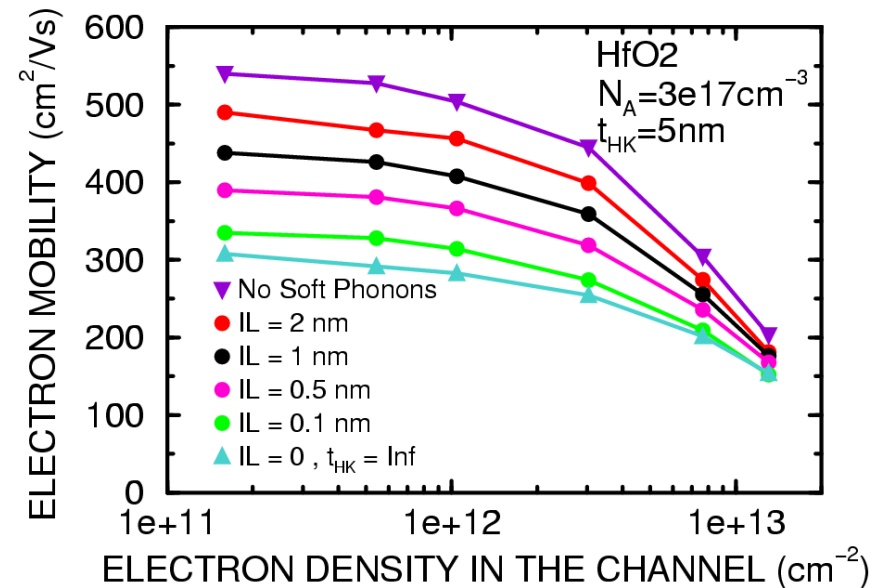
Comparison between 3DMC and MSMC models



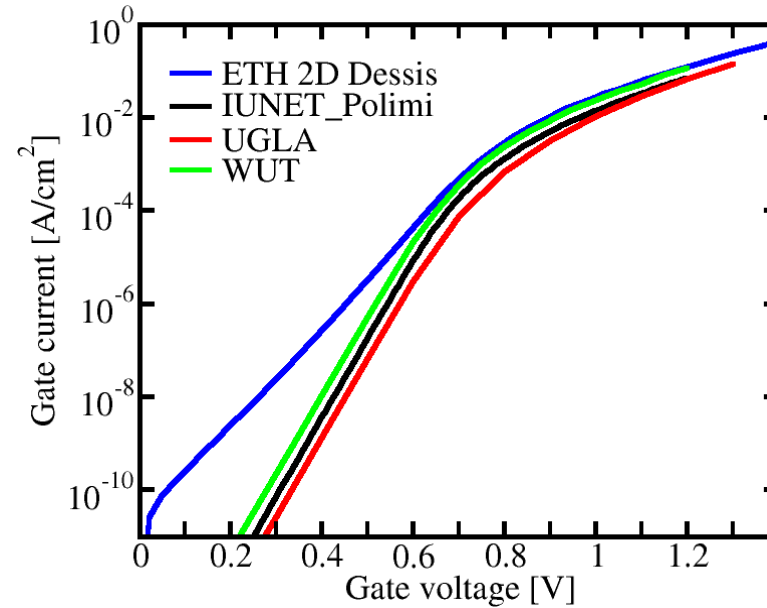
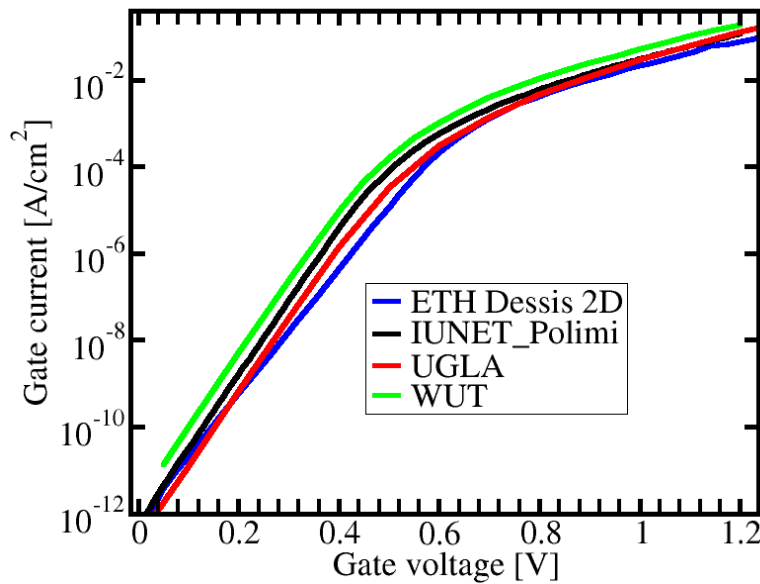
Introduction of High-k materials in the gate stack

Develop new physical models and evaluate the impact of different technology options on the channel mobility.

Remote optical phonon scattering



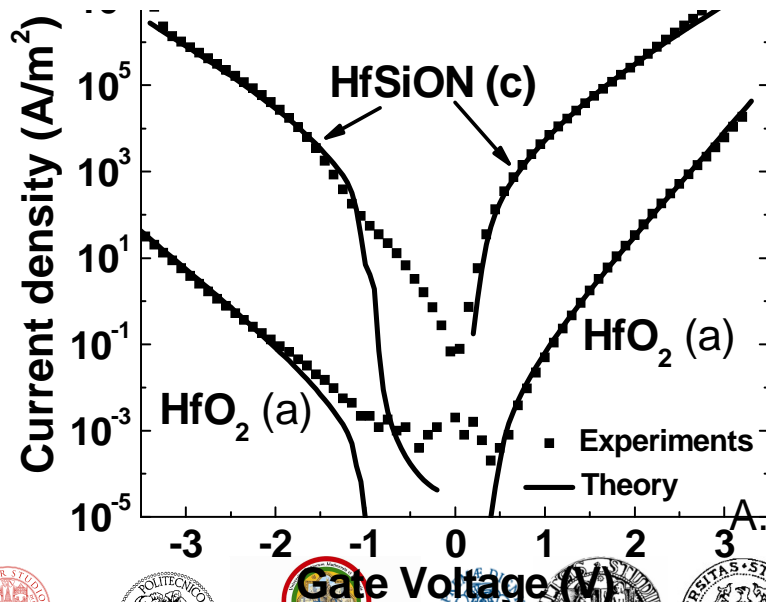
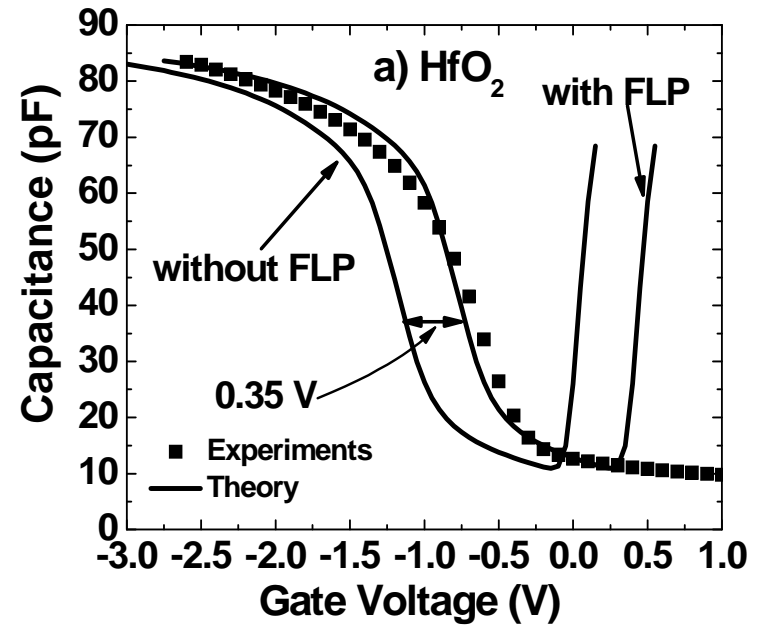
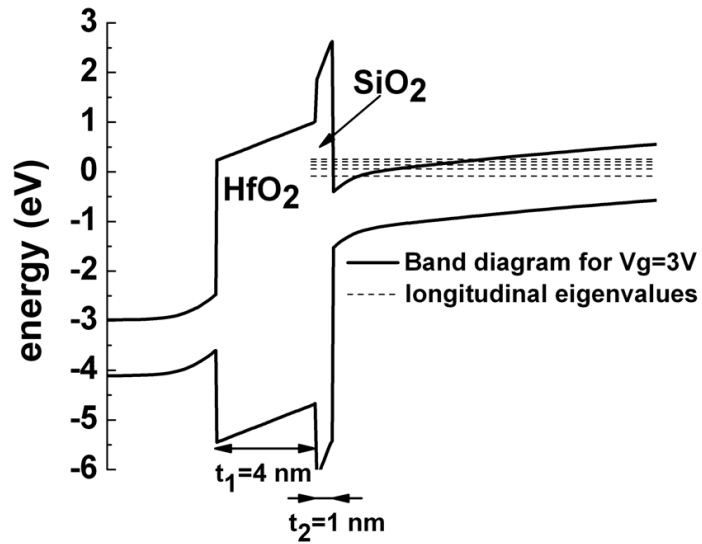
# Comparison of gate currents in high-K stacks (POLIMI)



- Extension of the work performed in SINANO (tunneling contribution only)
- Results reported in D6452



# IUNET Transport in high-k stacks (PISA)



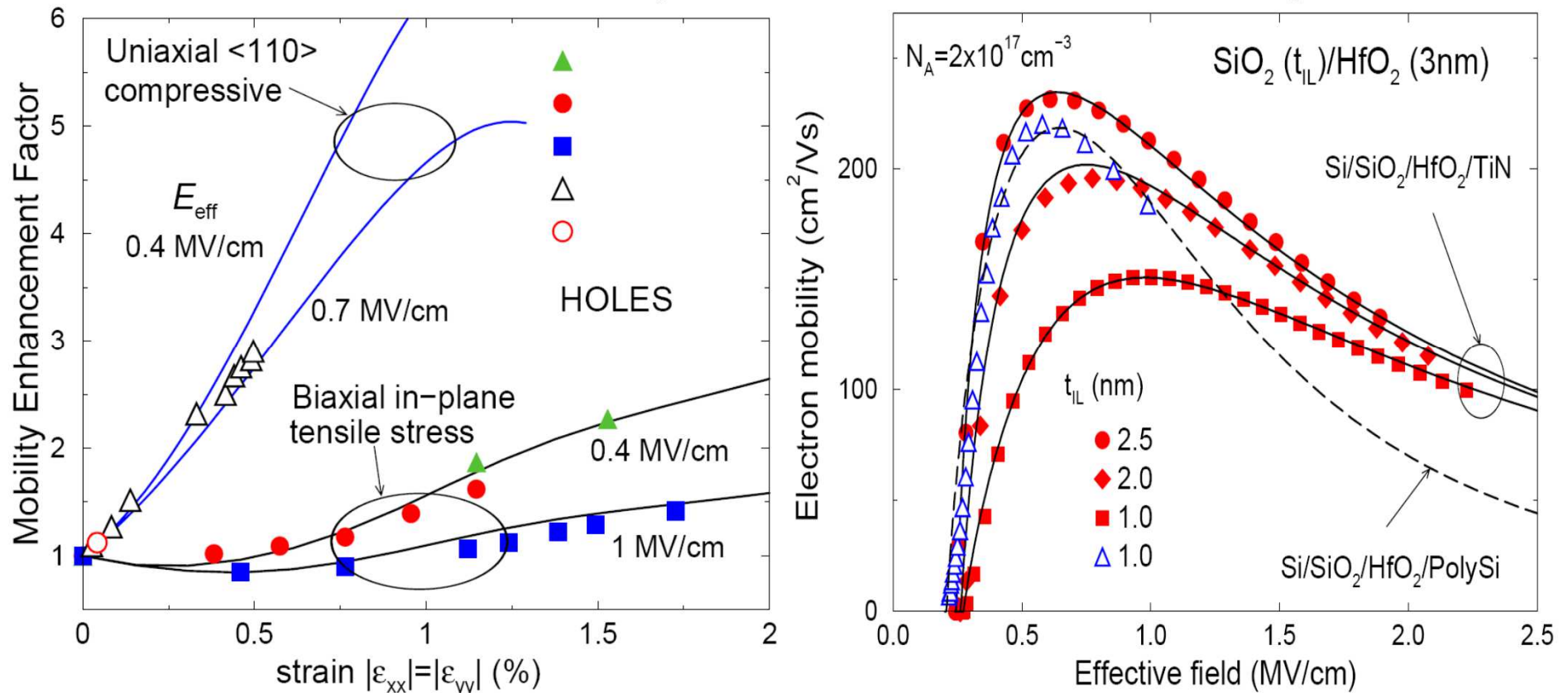
Par. extracted for HfO <sub>2</sub> , HfSiON and SiON			
	HfO <sub>2</sub>	HfSiON	SiON
Electron affinity	1.575 eV	1.97 eV	1.27 eV
Electron eff mass	0.08m <sub>0</sub>	0.24m <sub>0</sub>	0.45 m <sub>0</sub>
ε <sub>r</sub>	25	11	5
FLP	0.35 V	0.13 V	-

A. Campera, F. Crupi, G. Iannaccone, TED 54, 83 2007

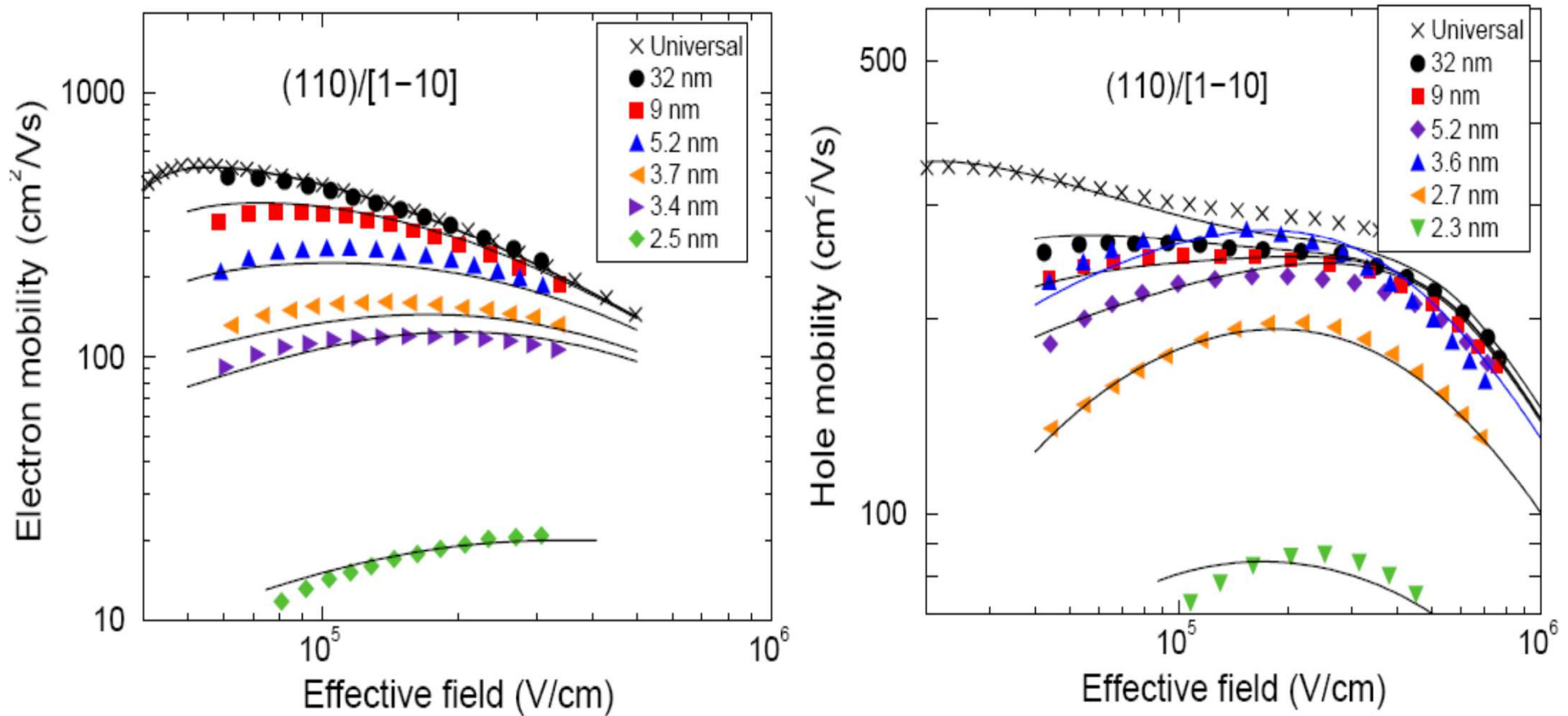


- Analytical mobility models for PDE based simulators
- Calibration w.r.t. extensive sets of experiments

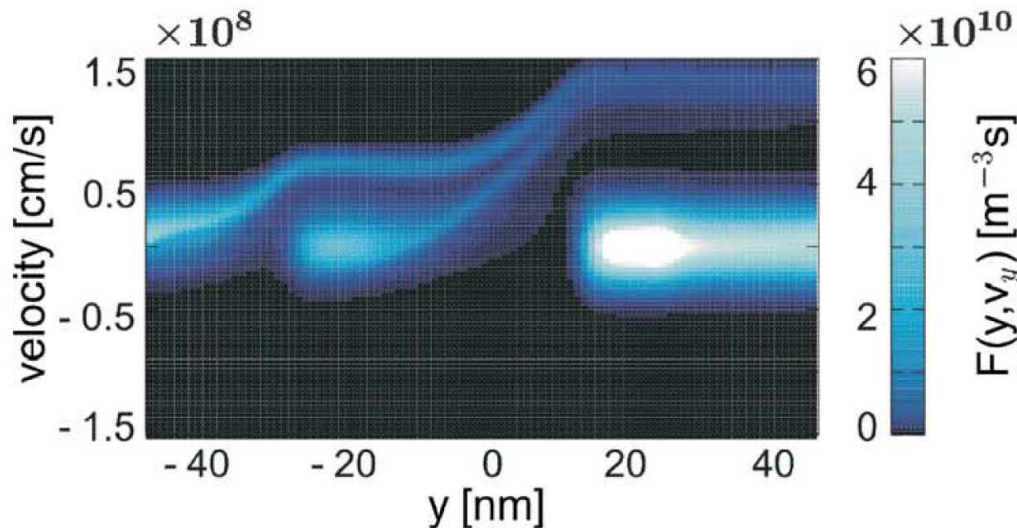
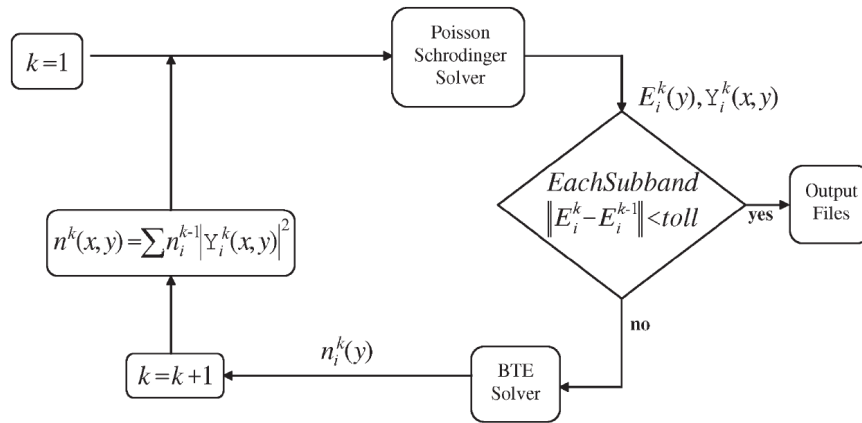
## Electron and hole mobility for strained silicon and high-k stacks



## Electron and hole mobility for ultra-thin body and different substrate/channel orientations



# Direct solution of the BTE for nanoMOSFETs (PISA)



- Reduced size of the phase space
- Deterministic solution of the BTE per subband
- Preliminary results based on two simplifying assumptions:

- No intersubband mixing
- relaxation time approximation

- S. Scaldaferrri et al., IEEE-TED, vol. 54, 2901 (2007).



Contents lists available at ScienceDirect

Solid-State Electronics

journal homepage: [www.elsevier.com/locate/sse](http://www.elsevier.com/locate/sse)



## A comparison of advanced transport models for the computation of the drain current in nanoscale nMOSFETs

P. Palestri<sup>a,\*</sup>, C. Alexander<sup>b</sup>, A. Asenov<sup>b</sup>, V. Aubry-Fortuna<sup>d</sup>, G. Bacarani<sup>c</sup>, A. Bournel<sup>d</sup>, M. Braccioli<sup>e</sup>, B. Cheng<sup>b</sup>, P. Dollfus<sup>d</sup>, A. Esposito<sup>f</sup>, D. Esseni<sup>a</sup>, C. Fenouillet-Beranger<sup>j,k</sup>, C. Fiegna<sup>e</sup>, G. Fiori<sup>h</sup>, A. Ghetti<sup>g</sup>, G. Iannaccone<sup>h</sup>, A. Martinez<sup>b</sup>, B. Majkusiak<sup>i</sup>, S. Monfray<sup>j</sup>, V. Peikert<sup>f</sup>, S. Reggiani<sup>c</sup>, C. Riddet<sup>b</sup>, J. Saint-Martin<sup>d</sup>, E. Sangiorgi<sup>e</sup>, A. Schenk<sup>f</sup>, L. Selmi<sup>a</sup>, L. Silvestri<sup>c</sup>, P. Toniutti<sup>a</sup>, J. Walczak<sup>i</sup>

### Acknowledgment

This work was partially funded by the E.U. through the PULL-NANO Project, IST-026828.

<sup>a</sup> DIEGM, University of Udine – IU.NET, Via delle Scienze 208, 33100 Udine, Italy

<sup>b</sup> University of Glasgow, Glasgow, UK

<sup>c</sup> ARCES, University of Bologna – IU.NET, Bologna, Italy

<sup>d</sup> IEF, University Paris–Sud, CNRS, Orsay, France

<sup>e</sup> ARCES, University of Bologna – IU.NET, Cesena, Italy

<sup>f</sup> ETH Zürich, Gloriastrasse 35, CH-8092 Zürich, Switzerland

<sup>g</sup> Numonyx, R&D – Technology Development, Via Olivetti 2, 20041 Agrate Brianza, Italy

<sup>h</sup> University of Pisa – IU.NET, Pisa, Italy

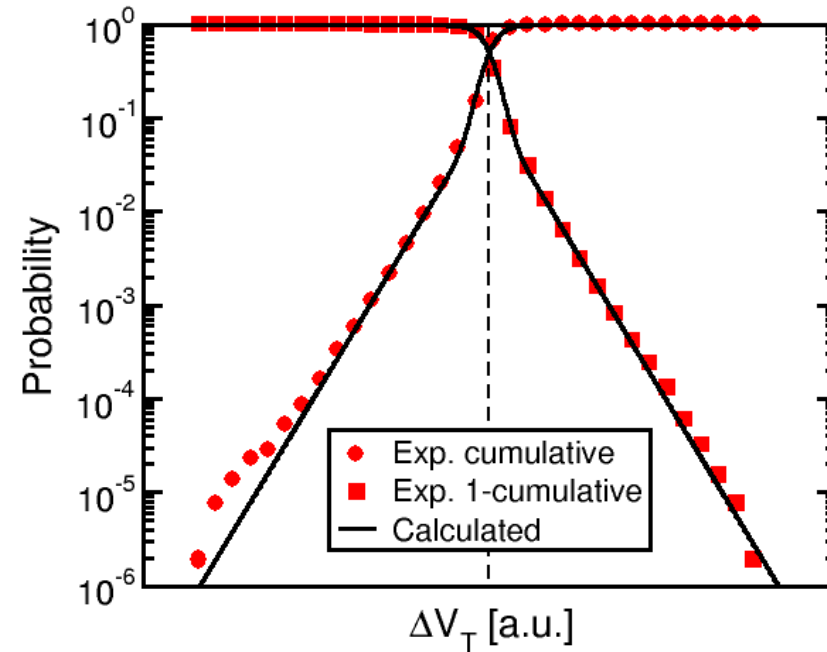
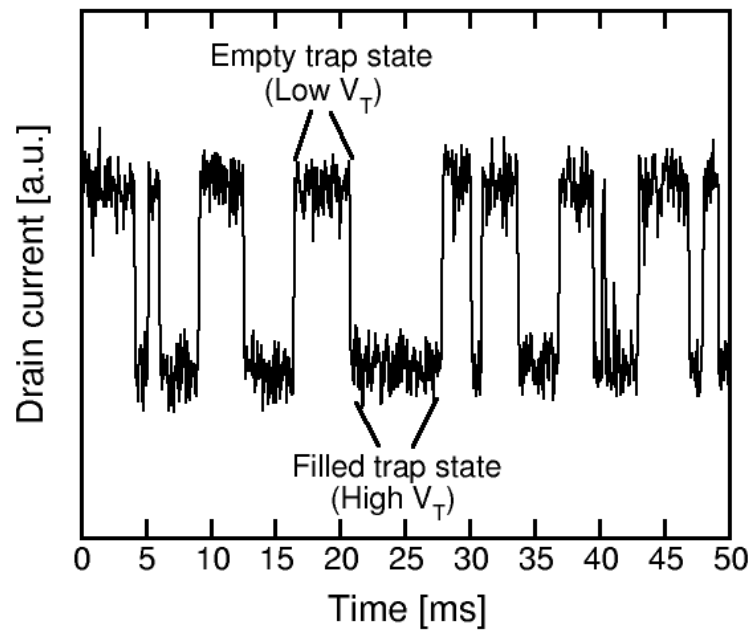
<sup>i</sup> Warsaw University of Technology, Warsaw, Poland

<sup>j</sup> ST Microelectronics, Crolles, France

<sup>k</sup> CEA/MINATEC/LETI, 17 rue des Martyrs, 38054 Grenoble, France

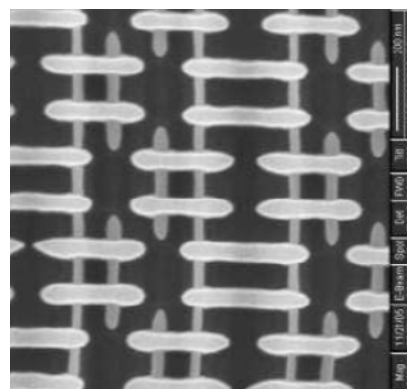
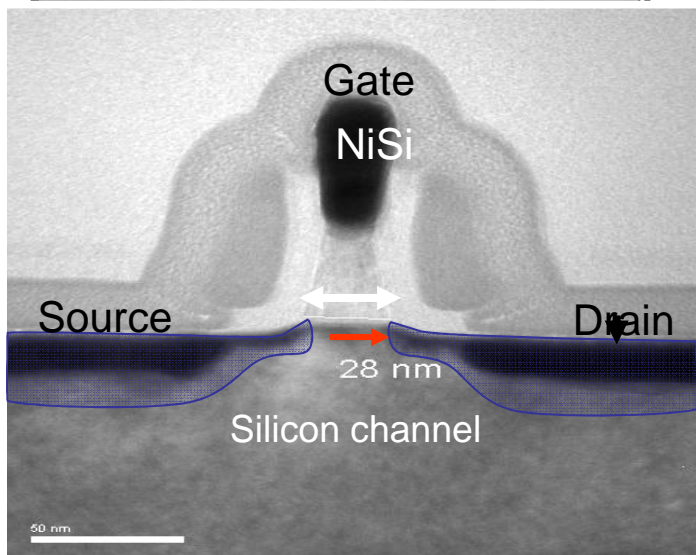
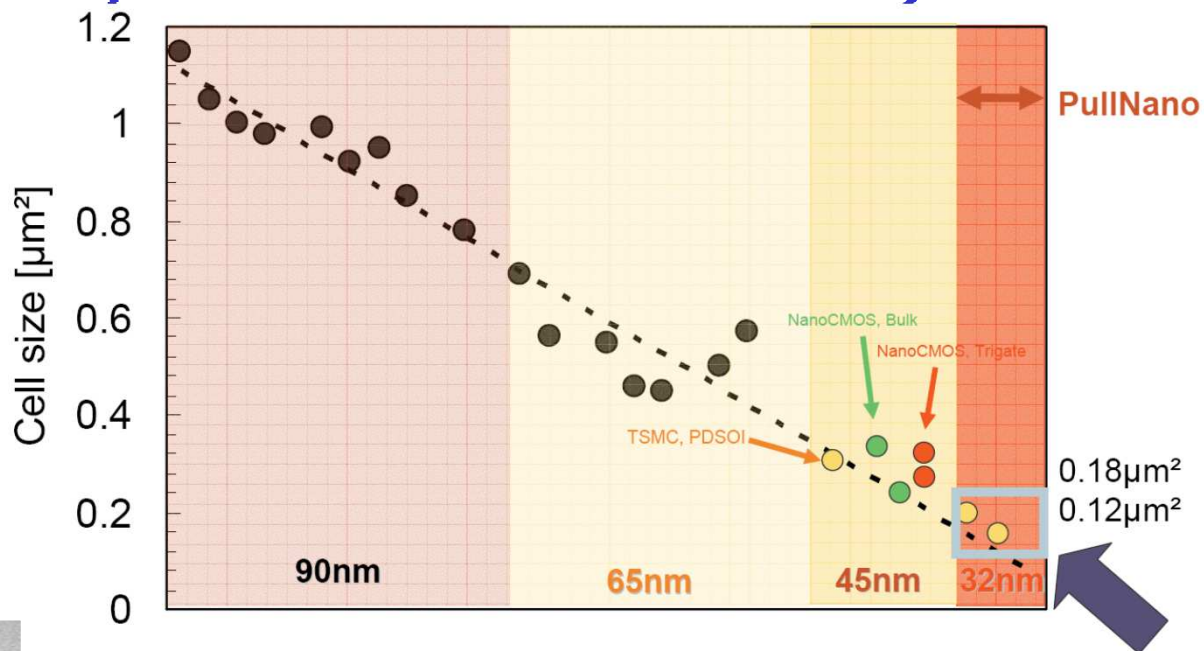
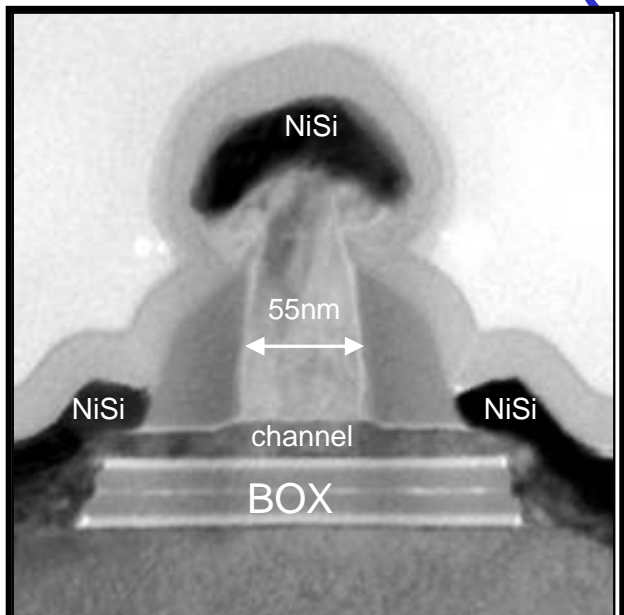


# Fluctuations at device level (POLIMI)



- Analysis of RTN in Flash NOR devices
- Results reported in D6411

# Achievements (in spite of NXP default)





# The End



- Sostanziale aderenza al piano delle attività
  - Difficoltà nel giustificare alcune attività (pertinenza, overlap)
  - Positiva evoluzione di alcune attività durante il progetto
  - Definire con chiarezza ad inizio progetto chi fa cosa
  - Convergenza dei temi di ricerca tra gruppi di IUNET
  - Creazione di opportunità per nuovi partner IUNET
- 
- Un nuovo modello di relazioni Industria-Accademia nei progetti
  - Coagulazione di un gruppo di partner accademici «accreditati»